



Material Content Data Sheet



Sales Product Name	TLE4254GA			Issued	24. January 2018			
MA#	MA001370038							
Package	PG-DSO-8-46			Weight*	82.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.779	2.14	2.14	21447	21447
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		436	
	non noble metal	iron	7439-89-6	0.723	0.87		8723	
wire	non noble metal	copper	7440-50-8	29.372	35.42	36.34	354171	363439
	non noble metal	copper	7440-50-8	0.071	0.09	0.09	857	857
	organic material	carbon black	1333-86-4	0.098	0.12		1177	
encapsulation	plastics	epoxy resin	-	4.490	5.41		54146	
	inorganic material	silicondioxide	60676-86-0	44.221	53.34	58.87	533225	588548
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9936	9936
plating	noble metal	silver	7440-22-4	0.144	0.17	0.17	1738	1738
glue	plastics	epoxy resin	-	0.291	0.35		3509	
	noble metal	silver	7440-22-4	0.873	1.05	1.40	10526	14035
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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